

GPU SuperServer SYS-421GU-TNXR

Universal 4U Dual Processor (Intel) GPU System with NVIDIA HGX™ H100 4-GPU SXM5 board, NVLINK™ GPU-GPU Interconnect, and Redundant 3000W Titanium Level Power Supplies.



Key Applications

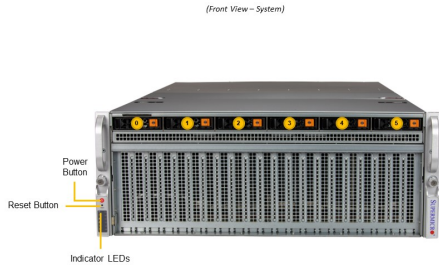
High Performance Computing, AI/Deep Learning Training,

Key Features

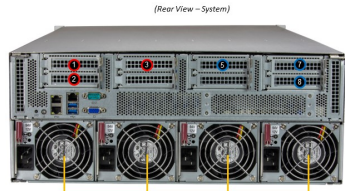
- 32 DIMM slots Up to 8TB: 32x 256 GB DRAM Memory Type: 4800MHz ECC DDR5;
- 8 PCIe Gen 5.0 X16 LP Slots;
- ; Flexible networking options;
- 6x 2.5" Hot-swap NVMe/SATA/SAS drive bays; 2 M.2 NVMe and SATA for boot drive only;



Form Factor	4U Rackmount Enclosure: 449 x 222.5 x 833mm (17.67" x 8.75" x 32.79") Package: 700 x 370 x 1260mm (27.55" x 14.57" x 49.6")
Processor	4th Gen Intel® Xeon® Scalable processors Dual Socket LGA-4677 (Socket E) supported (Supports up to 350W TDP CPUs (Air Cooled), Supports up to 350W TDP CPUs (Liquid Cooled))
GPU	Supported GPU: HGX H100 4-GPU SXM5 Multi-GPU Board CPU-GPU Interconnect: PCIe 5.0 x16 CPU-to-GPU Interconnect GPU-GPU Interconnect: NVIDIA® NVLink™
System Memory	32 DIMM slots Up to 8TB ECC LRDIMM, DDR5-4800MHz
Drive Bays	6x 2.5" hot-swap NVMe/SATA drive bays (6x 2.5" NVMe hybrid) 2 M.2 NVMe OR 2 M.2 SATA3
Expansion Slots	8 PCIe 5.0 X16 slot(s)
On-Board Devices	Chipset: Intel® C741 Network Connectivity: 2x 10GbE BaseT with Intel® X710-AT2 IPMI: Support for Intelligent Platform Management Interface v.2.0 IPMI 2.0 with virtual media over LAN and KVM-over-LAN support
Input / Output	Video: 1 VGA port(s)



Drive Bay	Description
(5)	6x 2.5" Hot-swap (NVMe/SATA3) Drive Bays



4x 3000W Redundant Titanium Level Power Supplies

Slot	Slot Description
1	PCIe 5.0 x16 (LP) via PLX2 for GPU2 RDMA
2	PCIe 5.0 x16 (LP)
3	PCIe 5.0 x16 (LP) from PLX3 for GPU1 RDMA
4	PCIe 5.0 x16 (LP) from PLX4 for GPU4 RDMA
5	PCIe 5.0 x16 (LP) from PLX3 for GPU3 RDMA
6	PCIe 5.0 x16 (LP)

GPU1 GPU2 GPU3 GPU4

System Cooling	5 heavy duty fan(s) Liquid Cooling: Direct to Chip (D2C) Cold Plate (optional)
Power Supply	6x 3000W (3+3) Redundant Power Supplies, Titanium Level Output Type: Backplanes (connector)
System BIOS	BIOS Type: AMI 32MB SPI Flash EEPROM
Management	SuperDoctor® 5; Watch Dog; NMI; SUM; KVM with dedicated LAN; SPM; Intel® Node Manager; SSM; IPMI 2.0; Redfish API; OOB Management Package (SFT-OOB-LIC)
PC Health Monitoring	CPU: Monitors for CPU Cores, Chipset Voltages, Memory 8+4 Phase-switching voltage regulator FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment Thermal Control for fan connectors
Dimensions and Weight	Height: 8.75" (222.5 mm) Width: 17.67" (449 mm) Depth: 32.79" (833 mm) Gross Weight: 225 lbs (102.1 kg) Net Weight: 166 lbs (75.3 kg) Packaging: 14.57" (H) x 27.55" (W) x 49.6" (D) Available Color: Black Front & Silver Body
Operating Environment	Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F) Non-operating Temperature: -40°C to 60°C (-40°F to 140°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)
Motherboard	Super X13DGU
Chassis	CSE-458GTS-R3K06P